

**SS103xxLF BOM-style material declaration. BI Technologies Corporation**

2/10/2011

No content banned per EU RoHS\.. Average mass of SS103xxLF thin film network is 0.09 gram. Prepared by Eric Arnold (714) 447-2565  
Weights in table above 1 milligram rounded to the nearest mg. Values less than 1 milligram given in scientific notation.

Sub-component	Material	% of total mass	Substance name	CAS #	Substance Weight (grams)	Special classification
Die	substrate	5.32%	Si	7440-21-3	0.0005	
		0.03%	SiO2, amorphous	7631-86-9	3.18E-06	
	nichrome resistor	0.0002%	NiCrOx	combination of 7440-02-0, 7440-47-3, & 1308-38-9	2.02E-08	
		0.0003%	Titanium tungsten alloy barrier	TiW	combination of 7440-02-0 & 7440-33-7	2.89E-08
	gold conductor	0.03%	Au	7440-57-5	2.72E-06	
	BCB passivation	0.009%	dvs-BCB, divinylsiloxane-bis-benzocyclobutene	124221-30-3	8.67E-07	
Leadframe	copper alloy	35.6%	Cu	7440-50-8	0.003	
			Fe	7439-89-6	7.86E-05	
			P	7723-14-0	1.00E-06	
			Zn	7440-66-6	4.01E-06	
			Sn	7440-31-5	0.0002	
			Ag	7440-22-4	0.0001	
Die adhesive	conductive epoxy	1.82%	Ag	7440-22-4	1.37E-04	
			trade secret	unknown	3.43E-05	non-hazardous
			Au	7440-57-5	6.26E-06	
Wire bonds	gold	0.07%	Au	7440-57-5	6.26E-06	
Molding compound	filled epoxy	54.20%	carbon black	1333-86-4	2.55E-05	
			epoxy resin, cresol novolac	29690-82-2	0.000	
			SiO2, fused silica	60676-86-0	0.004	
			trade secret	unknown	0.001	non-hazardous